



# 10NM90

*Power MOSFET*

## 10A, 900V N-CHANNEL SUPER-JUNCTION MOSFET

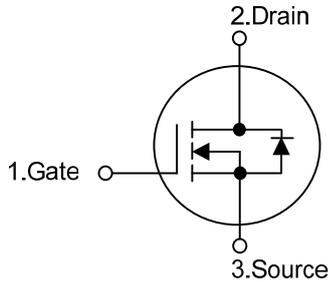
### DESCRIPTION

The **UTC 10NM90** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

### FEATURES

- \*  $R_{DS(ON)} \leq 1.0 \Omega$  @  $V_{GS}=10V, I_D=5.0A$
- \* Fast switching capability
- \* Avalanche energy tested
- \* Improved dv/dt capability, high ruggedness

### SYMBOL

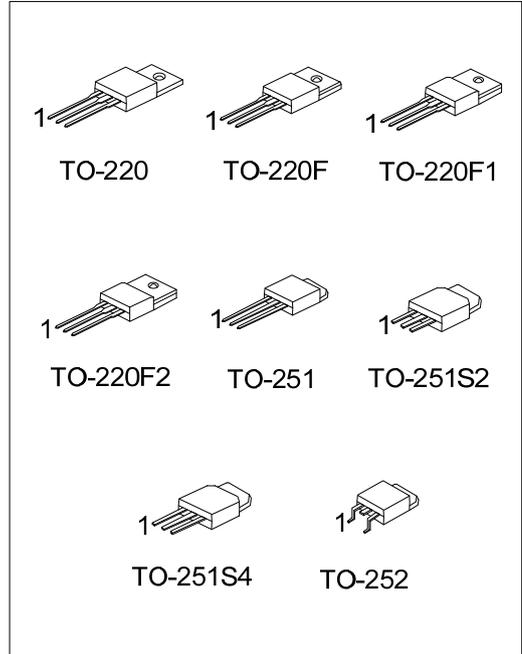


### ORDERING INFORMATION

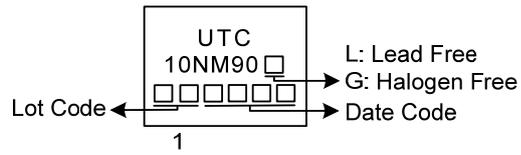
Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
10NM90L-TA3-T	10NM90G-TA3-T	TO-220	G	D	S	Tube
10NM90L-TF1-T	10NM90G-TF1-T	TO-220F1	G	D	S	Tube
10NM90L-TF2-T	10NM90G-TF2-T	TO-220F2	G	D	S	Tube
10NM90L-TF3-T	10NM90G-TF3-T	TO-220F	G	D	S	Tube
10NM90L-TM3-T	10NM90G-TM3-T	TO-251	G	D	S	Tube
10NM90L-TMS2-T	10NM90G-TMS2-T	TO-251S2	G	D	S	Tube
10NM90L-TMS4-T	10NM90G-TMS4-T	TO-251S4	G	D	S	Tube
10NM90L-TN3-R	10NM90G-TN3-R	TO-252	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>10NM90G-TA3-T</p>	<p>(1) T: Tube, R: Tape Reel                  (2) TA3: TO-220, TF1: TO-220F1, TF2: TO-220F2, TF3: TO-220F, TM3: TO-251, TMS2: TO-251S2, TMS4: TO-251S4, TN3: TO-252                  (3) G: Halogen Free and Lead Free, L: Lead Free</p>
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■ MARKING



■ ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ , unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	900	V
Gate-Source Voltage		$V_{GSS}$	$\pm 30$	V
Continuous Drain Current	Continuous	$I_D$	10	A
Pulsed Drain Current	Pulsed (Note 2)	$I_{DM}$	30	A
Single Pulsed Avalanche Energy	Single Pulsed (Note 3)	$E_{AS}$	288	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	2.4	V/ns
Power Dissipation	TO-220	$P_D$	70	W
	TO-220F/TO-220F1		24	W
	TO-220F2			
	TO-251/TO-25S2 TO-251S4/TO-252		38	W
Junction Temperature		$T_J$	+150	$^\circ\text{C}$
Storage Temperature		$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3.  $L = 100\text{mH}$ ,  $I_{AS} = 2.4\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .

4.  $I_{SD} \leq 10\text{A}$ ,  $di/dt \leq 200\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$ .

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient	TO-220/TO-220F TO-220F/TO-220F2	$\theta_{JA}$	62.5	$^\circ\text{C}/\text{W}$
	TO-251/TO-25S2 TO-251S4/TO-252		110	$^\circ\text{C}/\text{W}$
	TO-220		1.78	$^\circ\text{C}/\text{W}$
Junction to Case	TO-220F/TO-220F1 TO-220F2	$\theta_{JC}$	5.2	$^\circ\text{C}/\text{W}$
	TO-251/TO-25S2 TO-251S4/TO-252		3.28 (Note)	$^\circ\text{C}/\text{W}$

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

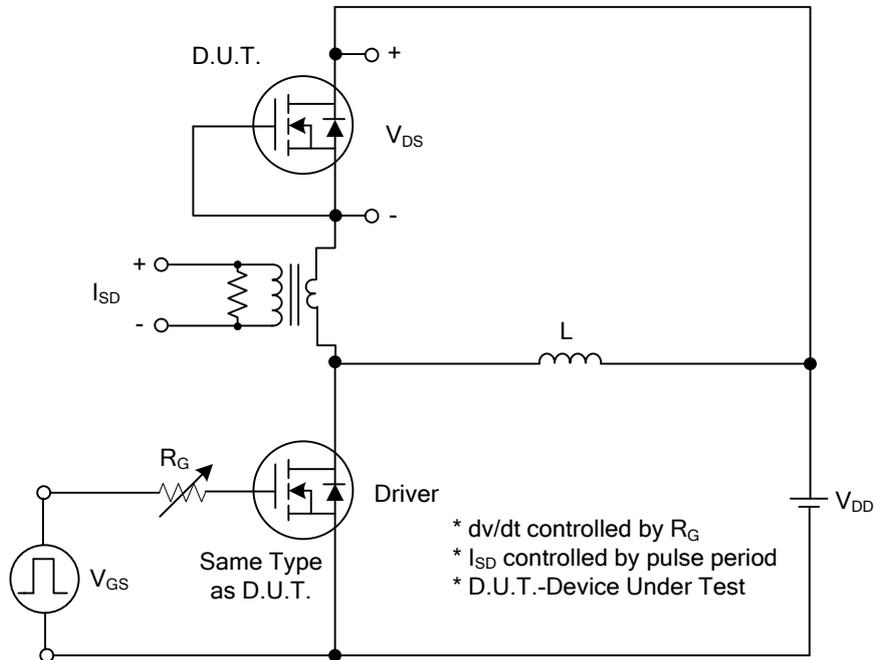
■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	900			V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =900V, V <sub>GS</sub> =0V			10	μA
Gate-Source Leakage Current	Forward	I <sub>GSS</sub> V <sub>GS</sub> =30V, V <sub>DS</sub> =0V			100	nA
	Reverse		V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V			-100
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.5		4.5	V
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.0A			1.0	Ω
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =50V, f=1.0MHz		940		pF
Output Capacitance	C <sub>OSS</sub>			78		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			4.5		pF
<b>SWITCHING CHARACTERISTICS</b>						
Total Gate Charge (Note 1)	Q <sub>G</sub>	V <sub>DS</sub> =720V, V <sub>GS</sub> =10V, I <sub>D</sub> =10A (Note1,2)		53		nC
Gate to Source Charge	Q <sub>GS</sub>			12		nC
Gate to Drain Charge	Q <sub>GD</sub>			20		nC
Turn-ON Delay Time (Note 1)	t <sub>D(ON)</sub>	V <sub>DD</sub> =100V, V <sub>GS</sub> =10V, I <sub>D</sub> =10A, R <sub>G</sub> =25Ω (Note1,2)		12		nS
Rise Time	t <sub>R</sub>			23		nS
Turn-OFF Delay Time	t <sub>D(OFF)</sub>			115		nS
Fall-Time	t <sub>F</sub>			56		nS
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Maximum Body-Diode Continuous Current	I <sub>S</sub>				10	A
Maximum Body-Diode Pulsed Current	I <sub>SM</sub>				30	A
Drain-Source Diode Forward Voltage (Note 1)	V <sub>SD</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V			1.4	V
Body Diode Reverse Recovery Time (Note 1)	t <sub>rr</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V, dI <sub>F</sub> /dt=100A/μs		440		nS
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>				6	

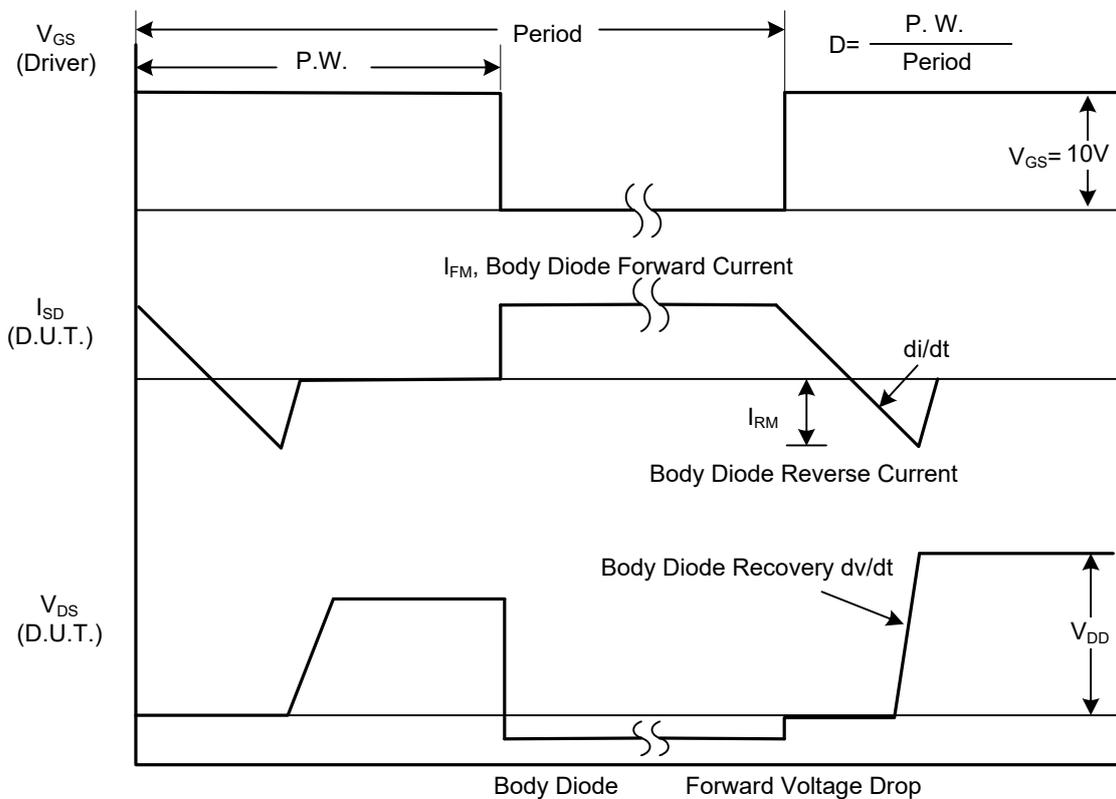
Notes: 1. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%.

2. Essentially independent of operating ambient temperature.

## TEST CIRCUITS AND WAVEFORMS

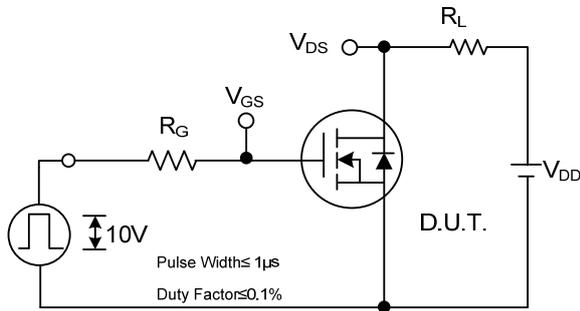


**Peak Diode Recovery  $dv/dt$  Test Circuit**

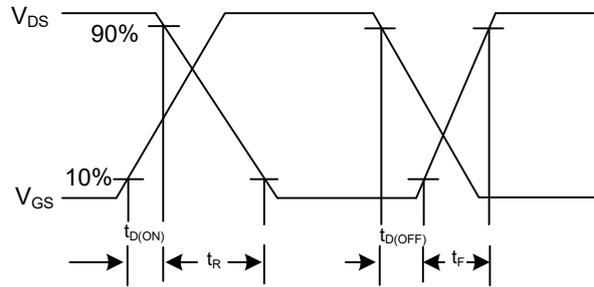


**Peak Diode Recovery  $dv/dt$  Waveforms**

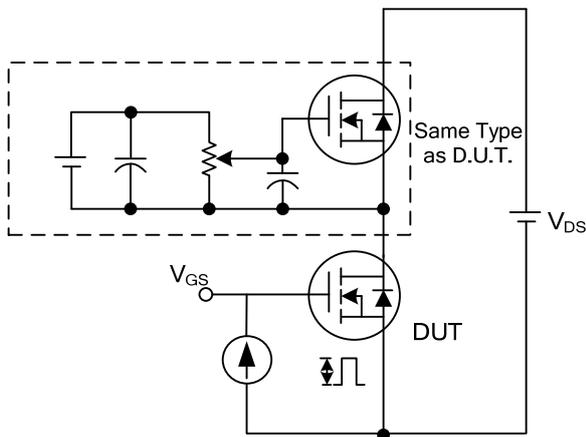
## ■ TEST CIRCUITS AND WAVEFORMS (Cont.)



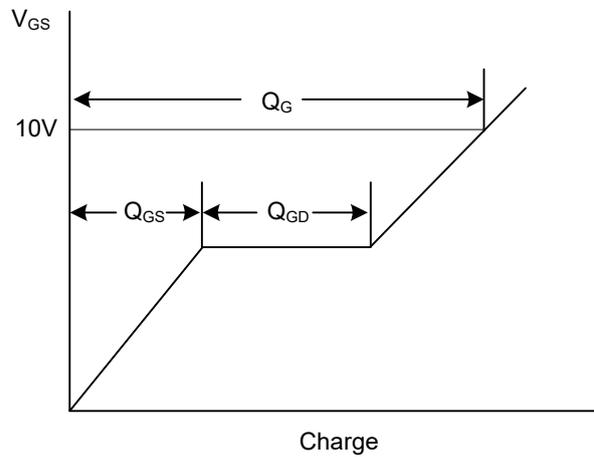
**Switching Test Circuit**



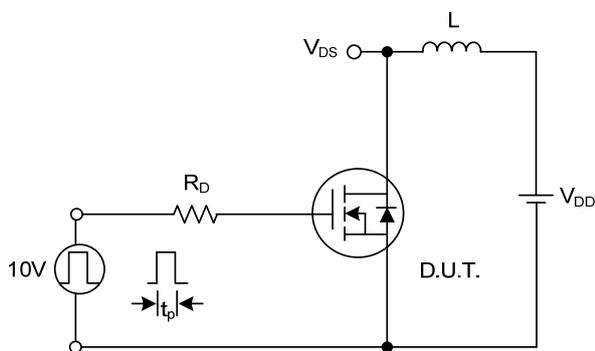
**Switching Waveforms**



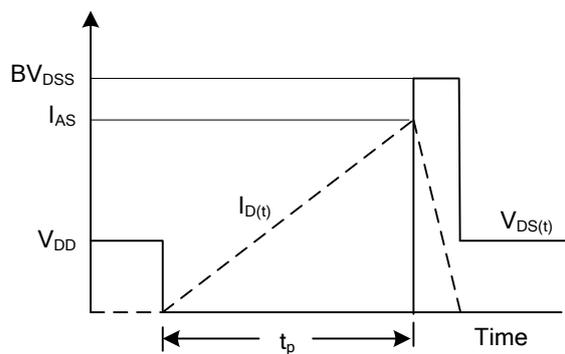
**Gate Charge Test Circuit**



**Gate Charge Waveform**

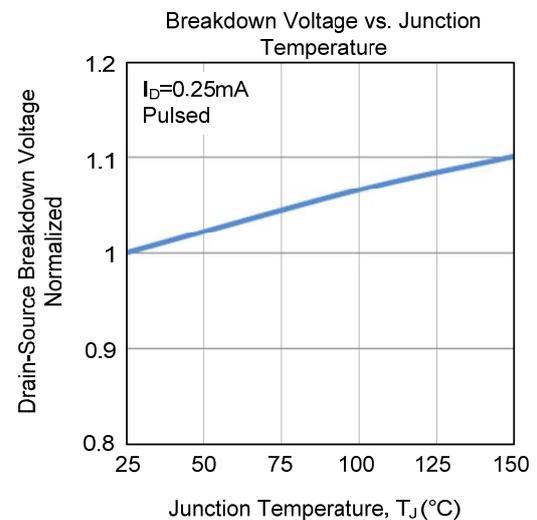
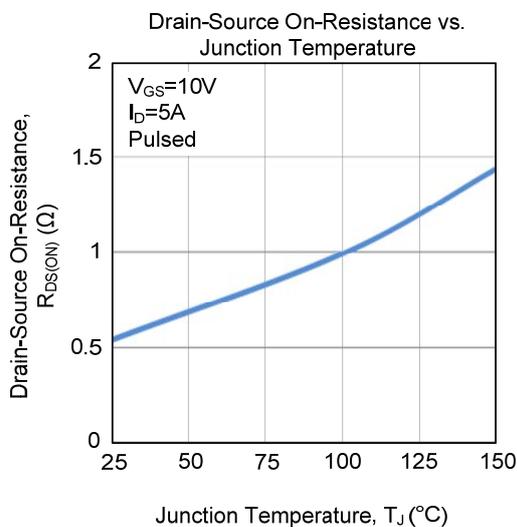
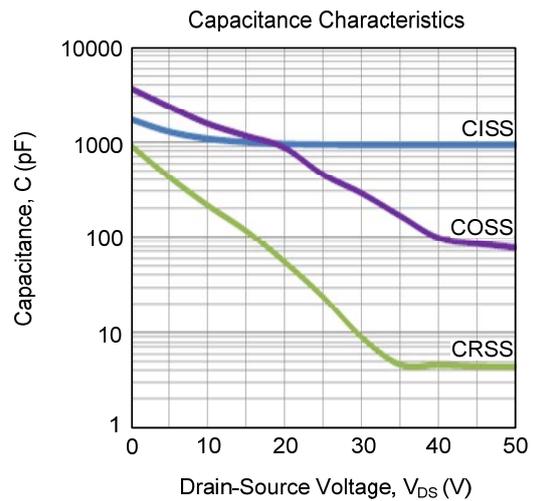
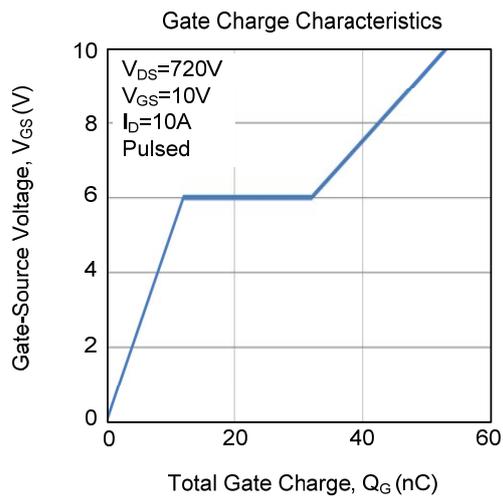
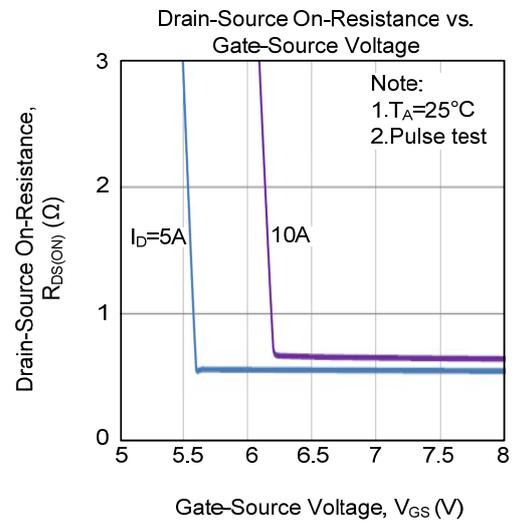
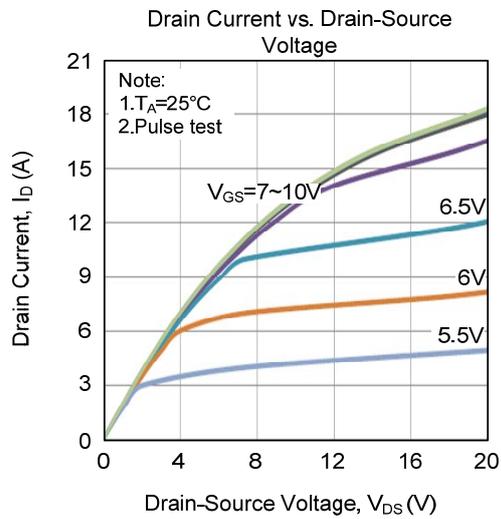


**Unclamped Inductive Switching Test Circuit**

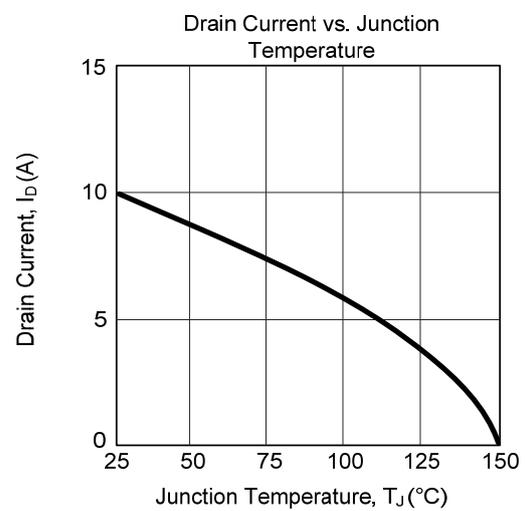
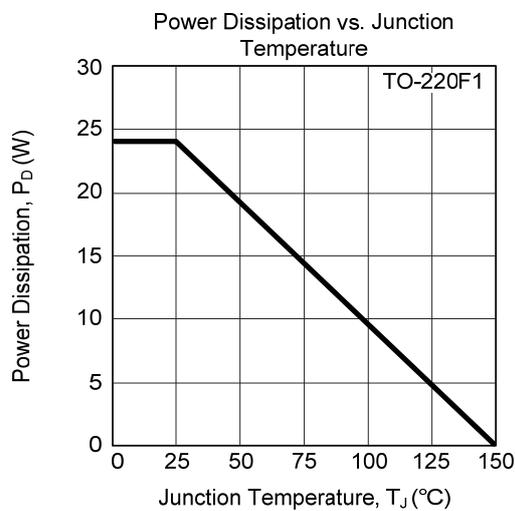
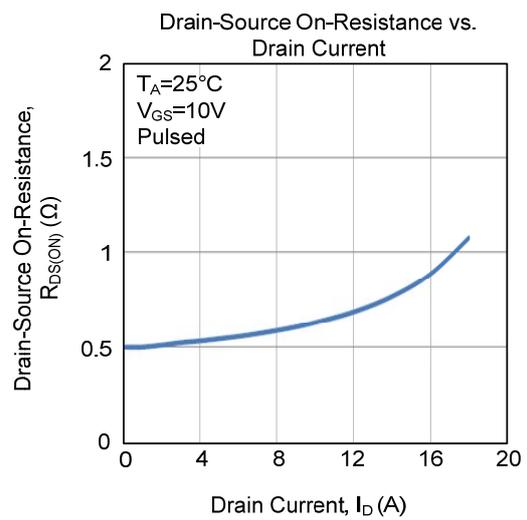
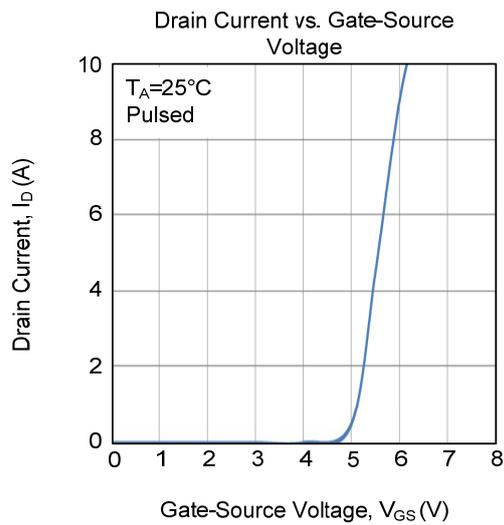
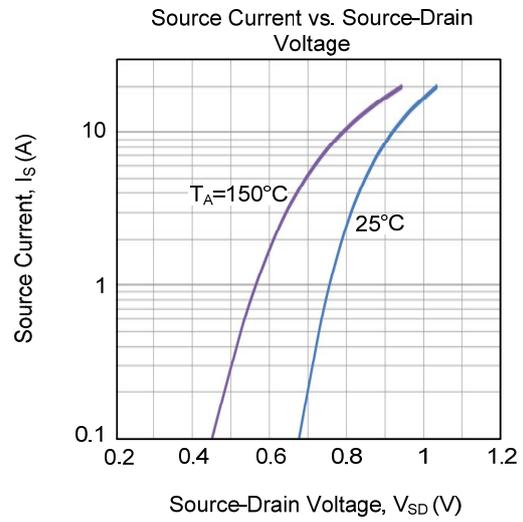
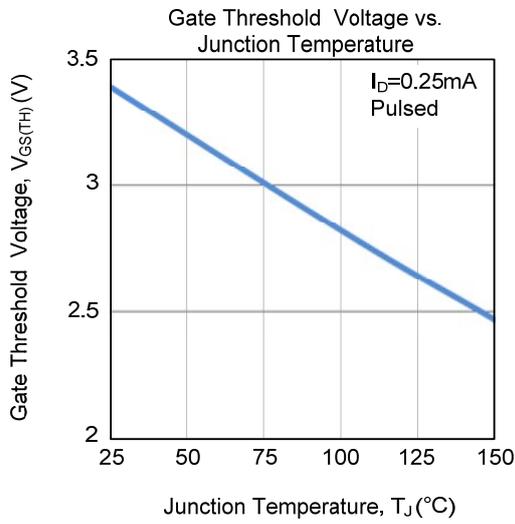


**Unclamped Inductive Switching Waveforms**

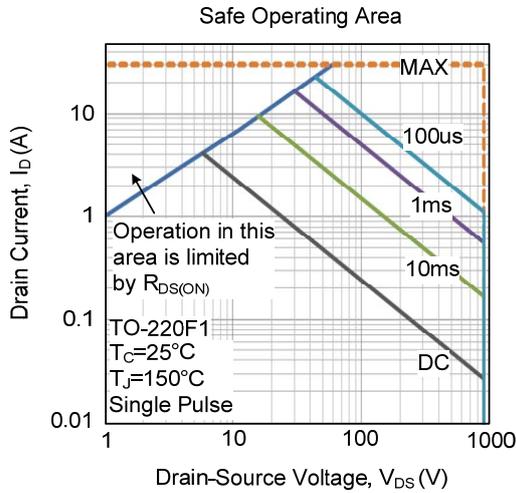
## TYPICAL CHARACTERISTICS



## ■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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